

Case Docket No. MICRON.241DV1

Date: November 7, 2003

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s)

Farrar et al.

Appl. No.

10/662,828

Filed

September 15, 2003

For

MULTIPLE CHIP STACK

STRUCTURE AND COOLING

**SYSTEM** 

Examiner

Unknown

Group Art Unit:

2815

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

November 10, 2003

Linda H. Lu, Reg No. 51,240

### TRANSMITTAL LETTER

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## Dear Sir:

Enclosed for filing in the above-identified application are:

- (X) An Information Disclosure Statement.
- (X) A PTO Form 1449 with fifty-four (54) references.
- (X) The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 11-1410.
- (X) Return prepaid postcard.

Linda H. Liu

Registration No. 51,240

Attorney of Record

Customer No. 20,995

(909) 781-9231

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	Examiner	:	Unknown		)	
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# INFORMATION DISCLOSURE STATEMENT

United States Patent and Trademark Office PO Box 2327 Arlington, VA 22202

## Dear Sir:

Enclosed is form PTO-1449 listing fifty-four (54) references that were previously disclosed to or cited by the Patent and Trademark Office in the prosecution of U.S. patent application No. 09/945,042, filed August 31, 2001, which is the parent of this application, and co-pending U.S. patent application No. 09/945,024, filed August 31, 2001 and is relied upon for an earlier filing date under 35 U.S.C. § 120. Copies of the references are not submitted pursuant to 37 C.F.R. § 1.98(d). However, copies will be provided at the request of the Examiner.

Appl. No.

: 09/945,024

Filed

: August 30, 2001

This Information Disclosure Statement is being filed with an RCE or within three months of the filing date of this application and no fee is required in accordance with 37 C.F.R. § 1.97(b)(1), (b)(2), or (b)(4).

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated:

By: \_

Linda H. Liu

Registration No. 51,240

Attorney of Record

Customer No. 20,995

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FORM TO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. MICRON.241DV1 APPLICATION NO. 10/662,828

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

APPLICANT Farrar et al.

(USE SEVERAL SHEETS IF NECESSARY)

FILING DATE GROUP September 15, 2003 . GROUP 2815

U.S. PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
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DATE CONSIDERED

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. MICRON.241DV1

APPLICATION NO. 10/662,828

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(USE SEVERAL SHEETS IF NECESSARY)

APPLICANT Farrar et al.

FILING DATE September 15, 2003 GROUP 2815

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INITIAL						YES	NO
	0 315 792 A2	10-1988	EP				

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FORM PTO-1449  U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  INFORMATION DISCLOSURE STATEMENT	ATTY. DOCKET NO. MICRON.241DV1	APPLICATION NO. 10/662,828
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(USE SEVERAL SHEETS IF NECESSARY)	FILING DATE September 15, 2003	GROUP 2815

	U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	(	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)	

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	"The New Low-k Candidate: It's A Gas"; Semiconductor International; March 1999, Pg. 38
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